Data sheet acquired from Cypress Semiconductor Corporation.
Data sheet modified to remove devices not offered.

CY74FCT2374T
CY74FCT2574T

8-Bit Registers

SCCS040 - September 1994 - Revised March 2000

Features

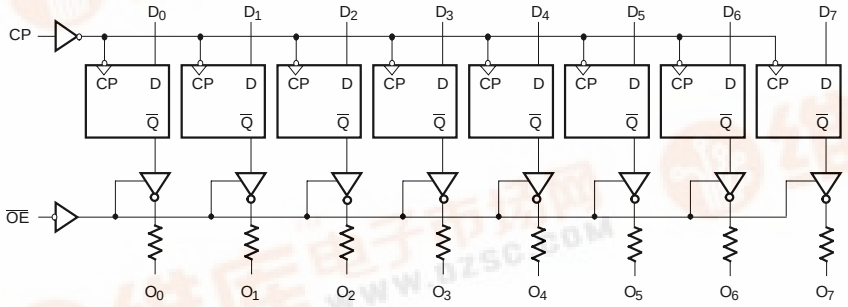
- **Function and pinout compatible with FCT and F logic**
- **25Ω output series resistors to reduce transmission line reflection noise**
- **FCT-C speed at 5.2 ns max.**
- **Reduced V_{OH} (typically=3.3V) versions of equivalent FCT functions**
- **Edge-rate control circuitry for significantly improved noise characteristics**
- **Power-off disable feature**
- **Matched rise and fall times**
- **Fully compatible with TTL input and output logic levels**
- **ESD > 2000V**
- **Sink current 12 mA**
  Source current 15 mA
- **Edge-triggered D-type inputs**
- **250 MHz typical toggle rate**
- **Extended commercial temp. range of –40˚C to +85˚C**

Functional Description

The FCT2374T and FCT2574T are high-speed low-power octal D-type flip-flops featuring separate D-type inputs for each flip-flop. On-chip termination resistors have been added to the outputs to reduce system noise caused by reflections. The FCT2374T and FCT2574T can be used to replace the FCT374T and FCT574T to reduce noise in an existing design. Both devices have three-state outputs for bus oriented applications. A buffered clock (CP) and output enable ($\overline{OE}$) are common to all flip-flops. The FCT2574T is identical to the FCT2374T except that all the outputs are on one side of the package and inputs on the other side. The flip-flops contained in the FCT2374T and FCT2574T will store the state of their individual D inputs that meet the set-up and hold time requirements on the LOW-to-HIGH clock (CP) transition. When $\overline{OE}$ is LOW, the contents of the flip-flops are available at the outputs. When $\overline{OE}$ is HIGH, the outputs will be in the high-impedence state. The state of output enable does not affect the state of the flip-flops.

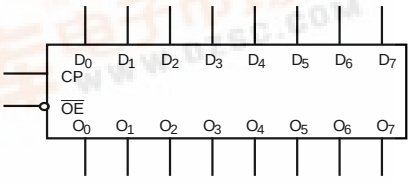
The outputs are designed with a power-off disable feature to allow for live insertion of boards.

Logic Block Diagram



FCT2374T-6

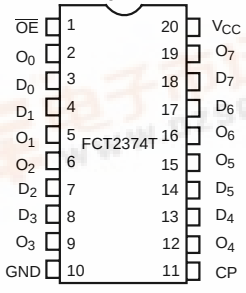
Logic Symbol



FCT2374T-5

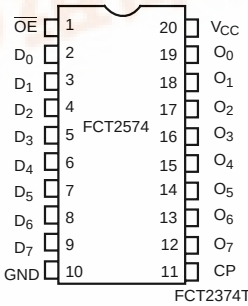
Pin Configurations

SOIC/QSOP
Top View



FCT2374T-2

SOIC/QSOP
Top View



FCT2374T-4

Function Table[1]

Inputs			Outputs
D	CP	$\overline{OE}$	O
H	⌐	L	H
L	⌐	L	L
X	X	H	Z

Maximum Ratings[2, 3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature .....–65°C to +150°C

Ambient Temperature with Power Applied.....–65°C to +135°C

Supply Voltage to Ground Potential..... –0.5V to +7.0V

DC Input Voltage ..... –0.5V to +7.0V

DC Output Voltage..... –0.5V to +7.0V

DC Output Current (Maximum Sink Current/Pin) .....120 mA

Power Dissipation 0.5W

Static Discharge Voltage.....>2001V (per MIL-STD-883, Method 3015)

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	–40°C to +85°C	5V ± 5%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Typ.[5]	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC}=Min., I_{OH}=–15 mA	2.4	3.3		V
V_{OL}	Output LOW Voltage	V_{CC}=Min., I_{OL}=12 mA		0.3	0.55	V
R_{OUT}	Output Resistance	V_{CC}=Min., I_{OL}=12 mA	20	25	40	Ω
V_{IH}	Input HIGH Voltage		2.0			V
V_{IL}	Input LOW Voltage				0.8	V
V_H	Hysteresis[6]	All inputs		0.2		V
V_{IK}	Input Clamp Diode Voltage	V_{CC}=Min., I_{IN}=–18 mA		–0.7	–1.2	V
I_I	Input HIGH Current	V_{CC}=Max., V_{IN}=V_{CC}			5	µA
I_{IH}	Input HIGH Current	V_{CC}=Max., V_{IN}=2.7V			±1	µA
I_{IL}	Input LOW Current	V_{CC}=Max., V_{IN}=0.5V			±1	µA
I_{OZH}	Off State HIGH-Level Output Current	V_{CC}=Max., V_{OUT}=2.7V			10	µA
I_{OZL}	Off State LOW-Level Output Current	V_{CC}=Max., V_{OUT}=0.5V			–10	µA
I_{OS}	Output Short Circuit Current[7]	V_{CC}=Max., V_{OUT}=0.0V	–60	–120	–225	mA
I_{OFF}	Power-Off Disable	V_{CC}=0V, V_{OUT}=4.5V			±1	µA

Capacitance[6]

Parameter	Description	Test Conditions	Typ. [5]	Max.	Unit
C_{IN}	Input Capacitance		5	10	pF
C_{OUT}	Output Capacitance		9	12	pF

Notes:

1. H = HIGH Voltage Level.
   L = LOW Voltage Level
   X = Don't Care
   Z = HIGH Impedance
   ⌐ = LOW-to-HIGH clock transition
2. Unless otherwise noted, these limits are over the operating free-air temperature range.
3. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
4. T_A is the "instant on" case temperature.
5. Typical values are at V_{CC}=5.0V, T_A=+25˚C ambient.
6. This parameter is specified but not tested.
7. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ.[5]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	V_{CC}=Max., $V_{IN}\leq$0.2V, $V_{IN}\geq V_{CC}$–0.2V	0.1	0.2	mA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs)	V_{CC}=Max., V_{IN}=3.4V,[8] f_1=0, Outputs Open	0.5	2.0	mA
I_{CCD}	Dynamic Power Supply Current[9]	V_{CC}=Max., One Input Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE}$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	0.06	0.12	mA/ MHz
I_C	Total Power Supply Current[10]	V_{CC}=Max., 50% Duty Cycle, Outputs Open, One Bit Toggling at f_1=5 MHz, f_0=10 MHz $\overline{OE}$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	0.7	1.4	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, One Bit Toggling at f_1=5 MHz, f_0=10 MHz $\overline{OE}$=GND, V_{IN}=3.4V or V_{IN}=GND	1.2	3.4	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f_1=2.5 MHz, Fo=10 MHz, $\overline{OE}$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	1.6	3.2[11]	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f_1=2.5 MHz, Fo=10 MHz, $\overline{OE}$=GND, V_{IN}=3.4V or V_{IN}=GND	3.9	12.2[11]	mA

Switching Characteristics Over the Operating Range[11]

Parameter	Description	CY74FCT2374T CY74FCT2574T		CY74FCT2374AT CY74FCT2574AT		CY74FCT2374CT CY74FCT2574CT		Unit	Fig. No.[13]
		Min.	Max.	Min.	Max.	Min.	Max.		
t_{PLH} t_{PHL}	Propagation Delay Clock to Output	2.0	10.0	2.0	6.5	2.0	5.2	ns	1, 5
t_{PZH} t_{PZL}	Output Enable Time	1.5	12.5	1.5	6.5	1.5	6.2	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	8.0	1.5	5.5	1.5	5.0	ns	1, 7, 8
t_S	Set-Up Time, HIGH or LOW D to CP	2.0		2.0		1.5		ns	4
t_H	Hold Time, HIGH or LOW D to CP	1.5		1.5		1.0		ns	4
t_W	Clk Pulse Width HIGH or LOW	7.0		5.0		4.0		ns	5

Notes:

8. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC}+\Delta I_{CC}D_HN_T+I_{CCD}(f_0/2 + f_1N_1)$
    I_{CC} = Quiescent Current with CMOS input levels
    ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
    D_H = Duty Cycle for TTL inputs HIGH
    N_T = Number of TTL inputs at D_H
    I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
    f_0 = Clock frequency for registered devices, otherwise zero
    f_1 = Input signal frequency
    N_1 = Number of inputs changing at f_1
    All currents are in milliamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.
12. Minimum limits are specified but not tested on Propagation Delays.
13. See “Parameter Measurement Information” in the General Information section.

Ordering Information

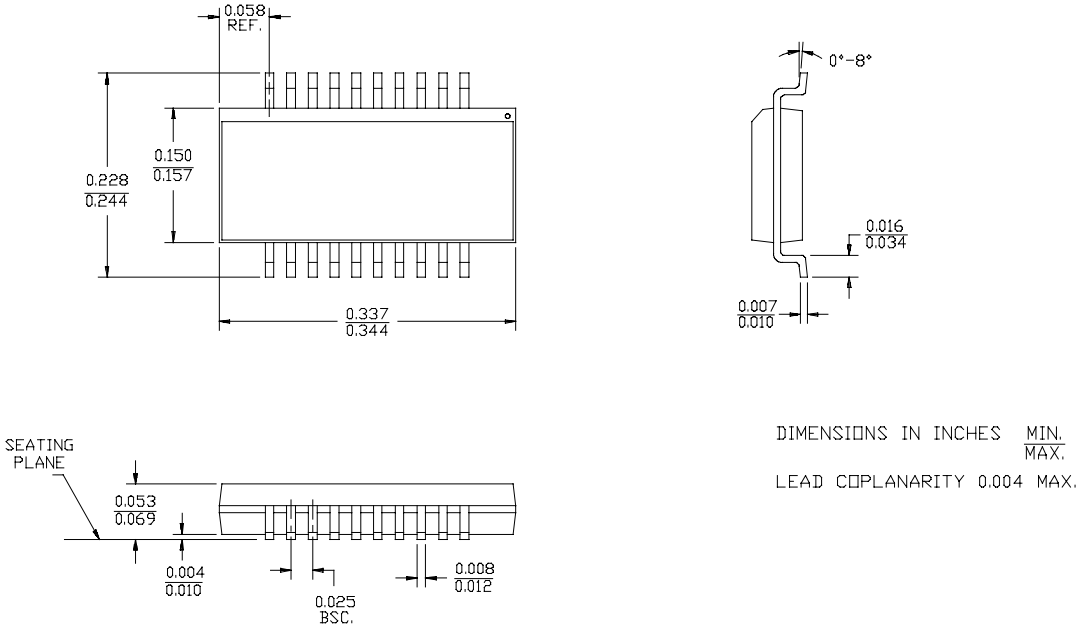
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
5.2	CY74FCT2374CTQCT	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT2374CTSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
6.5	CY74FCT2374ATQCT	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT2374ATSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
10.0	CY74FCT2374TSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	Commercial

Ordering Information

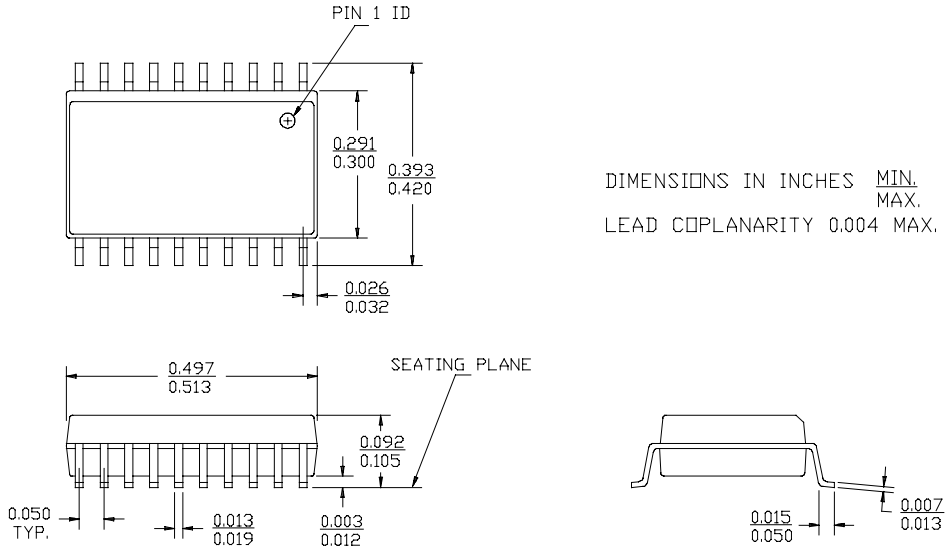
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
5.2	CY74FCT2574CTQCT	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT2574CTSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
6.5	CY74FCT2574ATQCT	Q5	20-Lead (150-Mil) QSOP	Commercial
10.0	CY74FCT2574TSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	Commercial

Package Diagrams

20-Lead Quarter Size Outline Q5



20-Lead (300-Mil) Molded SOIC S5



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